

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Masahiko KAWASE and  
Hidenobu KIMOTO.  
Divisional Application of Parent Serial No.: 09/690,870  
Filing Date: Concurrently herewith  
**For: A CHIP-TYPE COMPOSITE ELECTRONIC  
COMPONENT AND MANUFACTURING  
METHOD THEREOF**

#4/100-  
Amended  
AND  
8/09/02

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination on the merits, please amend the above-identified patent application as follows:

IN THE SPECIFICATION:

On page 1, before the first paragraph, please add the following new paragraph:

This application is a Divisional of U.S. Patent Application No. 09/690,870 filed October 17, 2000, currently pending.

IN THE CLAIMS:

Please cancel Claims 1-8 without prejudice or disclaimer of the subject matter contained therein.

BEST AVAILABLE COPY